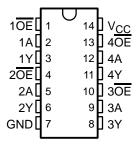
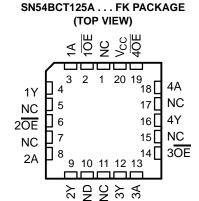
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- Operating Voltage Range of 4.5 V to 5.5 V
- State-of-the-Art BiCMOS Design Significantly Reduces I<sub>CCZ</sub>

SN54BCT125A . . . J OR W PACKAGE SN74BCT125A . . . D, N, OR NS PACKAGE (TOP VIEW)



### 3-State Outputs Drive Bus Lines or Buffer Memory Address Registers



NC - No internal connection

### description/ordering information

The 'BCT125A bus buffers feature independent line drivers with 3-state outputs. Each output is disabled when the associated output-enable (OE) input is high.

To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

#### ORDERING INFORMATION

TA	PACKA	GE <sup>†</sup>	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N	Tube	SN74BCT125AN	SN74BCT125AN
0°C to 70°C	SOIC - D	Tube	SN74BCT125AD	BCT125A
0 0 10 70 0	3010 - 0	Tape and reel	SN74BCT125ADR	BCT125A
	SOP - NS	Tape and reel	SN74BCT125ANSR	BCT125A
	CDIP – J	Tube	SNJ54BCT125AJ	SNJ54BCT125AJ
–55°C to 125°C	CFP – W	Tube	SNJ54BCT125AW	SNJ54BCT125AW
	LCCC – FK	Tube	SNJ54BCT125AFK	SNJ54BCT125AFK

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

# FUNCTION TABLE (each buffer)

INP	JTS	OUTPUT
OE	Α	Υ
L	Н	Н
L	L	L
Н	Χ	Z

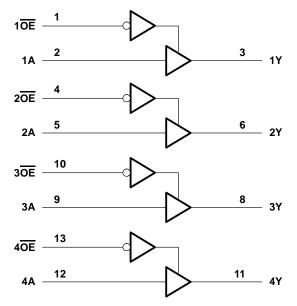


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SCBS032F - SEPTEMBER 1988 - REVISED MARCH 2003

### logic diagram (positive logic)



Pin numbers shown are for the D, J, N, NS, and W packages.

### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, V <sub>CC</sub>	–0.5 V to 7 V
Input voltage range, V <sub>I</sub> (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the disabled or power-off state, V <sub>O</sub>	–0.5 V to 5.5 V
Voltage range applied to any output in the high state, V <sub>O</sub>	–0.5 V to V <sub>CC</sub>
Input clamp current, $I_{ K }(V_{ } < 0)$	–30 mÅ
Current into any output in the low state, IO: SN54BCT125A	96 mA
SN74BCT125A	128 mA
Package thermal impedance, θ <sub>JA</sub> (see Note 2): D package	86°C/W
N package	80°C/W
NS package	
Storage temperature range, T <sub>stq</sub>	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.



SCBS032F - SEPTEMBER 1988 - REVISED MARCH 2003

### recommended operating conditions (see Note 3)

		SN54BCT125A		5A	SN7	UNIT		
		MIN	NOM	MAX	MIN	NOM	MAX	UNII
VCC	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2			2			V
V <sub>IL</sub>	Low-level input voltage			0.8			0.8	V
lıĸ	Input clamp current			-18			-18	mA
ЮН	High-level output current			-12			-15	mA
loL	Low-level output current			48			64	mA
TA	Operating free-air temperature	-55		125	0		70	°C

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED		TEST CONDITIONS			25A	SN7	74BCT12	25A	LINUT
PARAMETER	"5	SI CONDITIONS	MIN	TYP†	MAX	MIN	TYP†	MAX	UNIT
VIK	$V_{CC} = 4.5 \text{ V},$	I <sub>I</sub> = -18 mA			-1.2			-1.2	V
		$I_{OH} = -3 \text{ mA}$	2.4	3.3		2.4	3.3		
Voн	V <sub>CC</sub> = 4.5 V	$I_{OH} = -12 \text{ mA}$	2	3.2					V
		$I_{OH} = -15 \text{ mA}$				2	3.1		
Voi	V00 - 45 V	$I_{OL} = 48 \text{ mA}$		0.38	0.55				V
VOL	V <sub>CC</sub> = 4.5 V	$I_{OL} = 64 \text{ mA}$					0.42	0.55	V
ΙĮ	$V_{CC} = 0$ ,	V <sub>I</sub> = 7 V			0.1			0.1	mA
lіН	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 2.7 V			35			25	μΑ
I <sub>IL</sub>	$V_{CC} = 5.5 \text{ V},$	V <sub>I</sub> = 0.5 V			-20			-20	μΑ
<sup>l</sup> ozh	$V_{CC} = 5.5 \text{ V},$	V <sub>O</sub> = 2.7 V			50			50	μΑ
l <sub>OZL</sub>	$V_{CC} = 5.5 \text{ V},$	V <sub>O</sub> = 0.5 V			-50			-50	μΑ
los <sup>‡</sup>	V <sub>CC</sub> = 5.5 V,	VO = 0	-100		-225	-100		-225	mA
Іссн	V <sub>CC</sub> = 5.5 V,	Outputs open		19	31		19	31	mA
<sup>I</sup> CCL	V <sub>CC</sub> = 5.5 V,	Outputs open		46	49		46	49	mA
lccz	V <sub>CC</sub> = 5.5 V,	Outputs open		6	14		6	14	mA
C <sub>i</sub>	V <sub>CC</sub> = 5 V,	V <sub>I</sub> = 2.5 V or 0.5 V		4			4		pF
Co	V <sub>CC</sub> = 5 V,	V <sub>O</sub> = 2.5 V or 0.5 V		9			9		pF

<sup>†</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ .



<sup>‡</sup> Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

# SN54BCT125A, SN74BCT125A QUADRUPLE BUS BUFFER GATES WITH 3-STATE OUTPUTS SCBS032F - SEPTEMBER 1988 - REVISED MARCH 2003

### switching characteristics (see Figure 1)

PARAMETER	PARAMETER FROM (INPUT)		$V_{CC}$ = 5 V, $C_L$ = 50 pF, R1 = 500 Ω, R2 = 500 Ω, $T_A$ = 25°C			$V_{CC}$ = 4.5 V to 5.5 V, $C_L$ = 50 pF, R1 = 500 Ω, R2 = 500 Ω, $T_A$ = MIN to MAX§				UNIT	
			MIN	TYP	MAX	MIN	MAX	MIN	MAX		
t <sub>PLH</sub>		Y	1.6	3.5	5.2	1.6	6	1.6	5.7		
t <sub>PHL</sub>	Α		2.7	5	6.9	2.7	8	2.7	7.7	ns	
<sup>t</sup> PZH	ŌĒ	V	3.4	6.7	9	3.4	11.1	3.4	10.3	no	
t <sub>PZL</sub>	OE	Y	5	8.2	10.4	5	12.8	5	11.7	ns	
<sup>t</sup> PHZ	ŌĒ	V	3	5.8	7.4	3	9.4	3	8.9	nc	
t <sub>PLZ</sub>	J JL	1	2.8	5.5	7.3	2.8	9.9	2.8	8.6	ns	

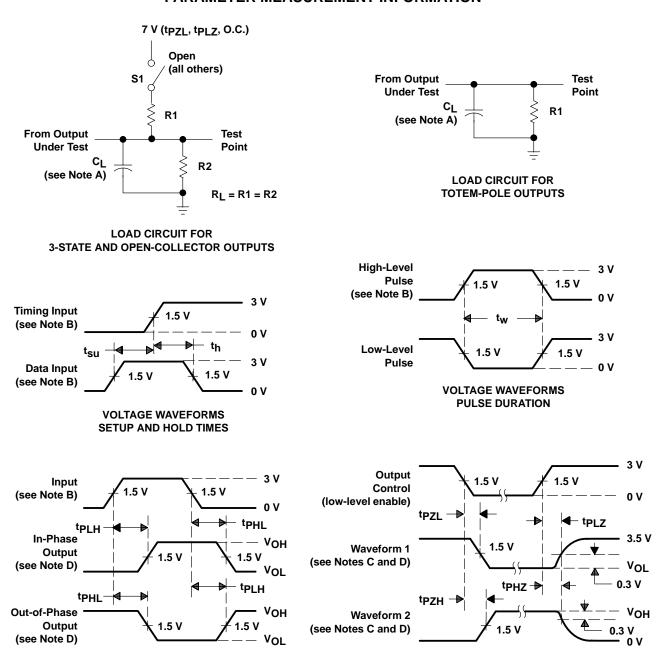
<sup>§</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



**VOLTAGE WAVEFORMS** 

**ENABLE AND DISABLE TIMES, 3-STATE OUTPUTS** 

#### PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>I</sub> includes probe and jig capacitance.

**VOLTAGE WAVEFORMS** PROPAGATION DELAY TIMES (see Note D)

- B. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $t_f = t_f \leq 2.5$  ns, duty cycle = 50%.
- C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- D. The outputs are measured one at a time with one transition per measurement.
- E. When measuring propagation delay times of 3-state outputs, switch S1 is open.
- F. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms



13-Jul-2022 www.ti.com

### **PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material (6)	MSL Peak Temp	Op Temp (°C)	<b>Device Marking</b> (4/5)	Samples
5962-9093701M2A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 9093701M2A SNJ54BCT 125AFK	Samples
5962-9093701MCA	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9093701MC A SNJ54BCT125AJ	Samples
5962-9093701MDA	ACTIVE	CFP	W	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9093701MD A SNJ54BCT125AW	Samples
SN54BCT125AJ	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54BCT125AJ	Samples
SN74BCT125AD	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	BCT125A	Samples
SN74BCT125ADG4	ACTIVE	SOIC	D	14	50	TBD	Call TI	Call TI	0 to 70		Samples
SN74BCT125ADR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	BCT125A	Samples
SN74BCT125AN	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74BCT125AN	Samples
SN74BCT125ANSR	ACTIVE	SO	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	BCT125A	Samples
SNJ54BCT125AFK	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 9093701M2A SNJ54BCT 125AFK	Samples
SNJ54BCT125AJ	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9093701MC A SNJ54BCT125AJ	Samples
SNJ54BCT125AW	ACTIVE	CFP	W	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9093701MD A SNJ54BCT125AW	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

### PACKAGE OPTION ADDENDUM

www.ti.com 13-Jul-2022

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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#### OTHER QUALIFIED VERSIONS OF SN54BCT125A, SN74BCT125A:

Catalog: SN74BCT125A

Military: SN54BCT125A

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

### **PACKAGE MATERIALS INFORMATION**

www.ti.com 9-Aug-2022

### TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74BCT125ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74BCT125ANSR	so	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

### **PACKAGE MATERIALS INFORMATION**

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#### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74BCT125ADR	SOIC	D	14	2500	356.0	356.0	35.0
SN74BCT125ANSR	SO	NS	14	2000	367.0	367.0	38.0

### **PACKAGE MATERIALS INFORMATION**

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### **TUBE**



\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
5962-9093701M2A	FK	LCCC	20	1	506.98	12.06	2030	NA
5962-9093701MDA	W	CFP	14	1	506.98	26.16	6220	NA
SN74BCT125AD	D	SOIC	14	50	506.6	8	3940	4.32
SN74BCT125AN	N	PDIP	14	25	506	13.97	11230	4.32
SN74BCT125AN	N	PDIP	14	25	506	13.97	11230	4.32
SNJ54BCT125AFK	FK	LCCC	20	1	506.98	12.06	2030	NA
SNJ54BCT125AW	W	CFP	14	1	506.98	26.16	6220	NA

### FK (S-CQCC-N\*\*)

### LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



### **MECHANICAL DATA**

### NS (R-PDSO-G\*\*)

## 14-PINS SHOWN

### PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



### W (R-GDFP-F14)

### CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14



CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.

4040083-5/G





CERAMIC DUAL IN LINE PACKAGE



- 1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This package is hermitically sealed with a ceramic lid using glass frit.
- His package is remitted by sealed with a ceramic its using glass mit.
   Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
   Falls within MIL-STD-1835 and GDIP1-T14.



CERAMIC DUAL IN LINE PACKAGE



### D (R-PDSO-G14)

### PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.



# D (R-PDSO-G14)

### PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



### N (R-PDIP-T\*\*)

### PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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